

Michael G Pecht

List of Publications by Year in descending order

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867
papers

31,055
citations

7561

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144
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965
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965
docs citations

965
times ranked

15996
citing authors

#	ARTICLE	IF	CITATIONS
1	Long Short-Term Memory Recurrent Neural Network for Remaining Useful Life Prediction of Lithium-Ion Batteries. IEEE Transactions on Vehicular Technology, 2018, 67, 5695-5705.	3.9	723
2	Prognostics of lithium-ion batteries based on Dempster-Shafer theory and the Bayesian Monte Carlo method. Journal of Power Sources, 2011, 196, 10314-10321.	4.0	670
3	Light emitting diodes reliability review. Microelectronics Reliability, 2012, 52, 762-782.	0.9	653
4	State of charge estimation of lithium-ion batteries using the open-circuit voltage at various ambient temperatures. Applied Energy, 2014, 113, 106-115.	5.1	623
5	Deep Residual Shrinkage Networks for Fault Diagnosis. IEEE Transactions on Industrial Informatics, 2020, 16, 4681-4690.	7.2	622
6	Battery Lifetime Prognostics. Joule, 2020, 4, 310-346.	11.7	570
7	Remaining Useful Life Estimation Based on a Nonlinear Diffusion Degradation Process. IEEE Transactions on Reliability, 2012, 61, 50-67.	3.5	460
8	An ensemble model for predicting the remaining useful performance of lithium-ion batteries. Microelectronics Reliability, 2013, 53, 811-820.	0.9	427
9	Remaining useful life prediction of lithium-ion battery with unscented particle filter technique. Microelectronics Reliability, 2013, 53, 805-810.	0.9	388
10	Prognostics for state of health estimation of lithium-ion batteries based on combination Gaussian process functional regression. Microelectronics Reliability, 2013, 53, 832-839.	0.9	373
11	Motor Bearing Fault Detection Using Spectral Kurtosis-Based Feature Extraction Coupled With k -Nearest Neighbor Distance Analysis. IEEE Transactions on Industrial Electronics, 2016, 63, 1793-1803.	5.2	372
12	Battery Management Systems in Electric and Hybrid Vehicles. Energies, 2011, 4, 1840-1857.	1.6	371
13	Prognostics and health management of electronics. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 222-229.	1.4	370
14	State of charge estimation for Li-ion batteries using neural network modeling and unscented Kalman filter-based error cancellation. International Journal of Electrical Power and Energy Systems, 2014, 62, 783-791.	3.3	369
15	A review of fractional-order techniques applied to lithium-ion batteries, lead-acid batteries, and supercapacitors. Journal of Power Sources, 2018, 390, 286-296.	4.0	367
16	Motor Bearing Fault Diagnosis Using Trace Ratio Linear Discriminant Analysis. IEEE Transactions on Industrial Electronics, 2014, 61, 2441-2451.	5.2	361
17	Influence of different open circuit voltage tests on state of charge online estimation for lithium-ion batteries. Applied Energy, 2016, 183, 513-525.	5.1	342
18	Effect of Temperature on the Aging rate of Li Ion Battery Operating above Room Temperature. Scientific Reports, 2015, 5, 12967.	1.6	339

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19	A review of lead-free solders for electronics applications. <i>Microelectronics Reliability</i> , 2017, 75, 77-95.	0.9	326
20	State of charge estimation for electric vehicle batteries using unscented kalman filtering. <i>Microelectronics Reliability</i> , 2013, 53, 840-847.	0.9	292
21	Prognostics of lithium-ion batteries based on relevance vectors and a conditional three-parameter capacity degradation model. <i>Journal of Power Sources</i> , 2013, 239, 253-264.	4.0	291
22	Deep Residual Networks With Dynamically Weighted Wavelet Coefficients for Fault Diagnosis of Planetary Gearboxes. <i>IEEE Transactions on Industrial Electronics</i> , 2018, 65, 4290-4300.	5.2	287
23	Degradation Data Analysis Using Wiener Processes With Measurement Errors. <i>IEEE Transactions on Reliability</i> , 2013, 62, 772-780.	3.5	284
24	A prognostics and health management roadmap for information and electronics-rich systems. <i>Microelectronics Reliability</i> , 2010, 50, 317-323.	0.9	272
25	Lithium-Ion Battery Health Prognosis Based on a Real Battery Management System Used in Electric Vehicles. <i>IEEE Transactions on Vehicular Technology</i> , 2019, 68, 4110-4121.	3.9	269
26	Lessons Learned from the 787 Dreamliner Issue on Lithium-Ion Battery Reliability. <i>Energies</i> , 2013, 6, 4682-4695.	1.6	247
27	A failure modes, mechanisms, and effects analysis (FMMEA) of lithium-ion batteries. <i>Journal of Power Sources</i> , 2015, 297, 113-120.	4.0	234
28	Machine learning pipeline for battery state-of-health estimation. <i>Nature Machine Intelligence</i> , 2021, 3, 447-456.	8.3	227
29	A Double-Scale, Particle-Filtering, Energy State Prediction Algorithm for Lithium-Ion Batteries. <i>IEEE Transactions on Industrial Electronics</i> , 2018, 65, 1526-1538.	5.2	218
30	Battery warm-up methodologies at subzero temperatures for automotive applications: Recent advances and perspectives. <i>Progress in Energy and Combustion Science</i> , 2020, 77, 100806.	15.8	218
31	Li-Ion Battery Fire Hazards and Safety Strategies. <i>Energies</i> , 2018, 11, 2191.	1.6	207
32	Development of an optimized condition-based maintenance system by data fusion and reliability-centered maintenance. <i>Reliability Engineering and System Safety</i> , 2010, 95, 786-796.	5.1	194
33	Physics-of-failure-based prognostics for electronic products. <i>Transactions of the Institute of Measurement and Control</i> , 2009, 31, 309-322.	1.1	192
34	Sensor Systems for Prognostics and Health Management. <i>Sensors</i> , 2010, 10, 5774-5797.	2.1	192
35	Precursor Parameter Identification for Insulated Gate Bipolar Transistor (IGBT) Prognostics. <i>IEEE Transactions on Reliability</i> , 2009, 58, 271-276.	3.5	179
36	IoT-Based Prognostics and Systems Health Management for Industrial Applications. <i>IEEE Access</i> , 2016, 4, 3659-3670.	2.6	177

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37	A Prognostics and Health Management Roadmap for Information and Electronics-Rich Systems. <i>IEEE Fundamentals Review</i> , 2009, 3, 25-32.	0.1	172
38	Lithium-ion battery remaining useful life estimation based on fusion nonlinear degradation AR model and RPF algorithm. <i>Neural Computing and Applications</i> , 2014, 25, 557-572.	3.2	170
39	Advanced battery management strategies for a sustainable energy future: Multilayer design concepts and research trends. <i>Renewable and Sustainable Energy Reviews</i> , 2021, 138, 110480.	8.2	170
40	Diagnostics and Prognostics Method for Analog Electronic Circuits. <i>IEEE Transactions on Industrial Electronics</i> , 2013, 60, 5277-5291.	5.2	159
41	Lithium-Ion Battery Remaining Useful Life Prediction With Box-Cox Transformation and Monte Carlo Simulation. <i>IEEE Transactions on Industrial Electronics</i> , 2019, 66, 1585-1597.	5.2	159
42	No-fault-found and intermittent failures in electronic products. <i>Microelectronics Reliability</i> , 2008, 48, 663-674.	0.9	158
43	Benefits and Challenges of System Prognostics. <i>IEEE Transactions on Reliability</i> , 2012, 61, 323-335.	3.5	158
44	Application of a state space modeling technique to system prognostics based on a health index for condition-based maintenance. <i>Mechanical Systems and Signal Processing</i> , 2012, 28, 585-596.	4.4	154
45	Lifetime Estimation of High-Power White LED Using Degradation-Data-Driven Method. <i>IEEE Transactions on Device and Materials Reliability</i> , 2012, 12, 470-477.	1.5	148
46	MEMS Reliability Review. <i>IEEE Transactions on Device and Materials Reliability</i> , 2012, 12, 482-493.	1.5	148
47	Material failure mechanisms and damage models. <i>IEEE Transactions on Reliability</i> , 1991, 40, 531-536.	3.5	146
48	Vibration model of rolling element bearings in a rotor-bearing system for fault diagnosis. <i>Journal of Sound and Vibration</i> , 2013, 332, 2081-2097.	2.1	137
49	Multiple Wavelet Coefficients Fusion in Deep Residual Networks for Fault Diagnosis. <i>IEEE Transactions on Industrial Electronics</i> , 2019, 66, 4696-4706.	5.2	135
50	A prognostic approach for non-punch through and field stop IGBTs. <i>Microelectronics Reliability</i> , 2012, 52, 482-488.	0.9	134
51	Mitigation strategies for Li-ion battery thermal runaway: A review. <i>Renewable and Sustainable Energy Reviews</i> , 2021, 150, 111437.	8.2	128
52	Electronic part life cycle concepts and obsolescence forecasting. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2000, 23, 707-717.	1.4	126
53	A life consumption monitoring methodology for electronic systems. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2003, 26, 625-634.	1.4	123
54	Predicting long-term lumen maintenance life of LED light sources using a particle filter-based prognostic approach. <i>Expert Systems With Applications</i> , 2015, 42, 2411-2420.	4.4	123

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55	Cycle life testing and modeling of graphite/LiCoO ₂ cells under different state of charge ranges. Journal of Power Sources, 2016, 327, 394-400.	4.0	121
56	Predicting the reliability of electronic equipment. Proceedings of the IEEE, 1994, 82, 992-1004.	16.4	120
57	Deep Residual Networks With Adaptively Parametric Rectifier Linear Units for Fault Diagnosis. IEEE Transactions on Industrial Electronics, 2021, 68, 2587-2597.	5.2	117
58	Hygroscopic swelling and sorption characteristics of epoxy molding compounds used in electronic packaging. IEEE Transactions on Components and Packaging Technologies, 2003, 26, 206-214.	1.4	115
59	Estimation of remaining useful life of ball bearings using data driven methodologies. , 2012, , .		111
60	A generic model-free approach for lithium-ion battery health management. Applied Energy, 2014, 135, 247-260.	5.1	110
61	A Bayesian approach for Li-Ion battery capacity fade modeling and cycles to failure prognostics. Journal of Power Sources, 2015, 281, 173-184.	4.0	108
62	An Online SOC and SOH Estimation Model for Lithium-Ion Batteries. Energies, 2017, 10, 512.	1.6	107
63	Particle Learning Framework for Estimating the Remaining Useful Life of Lithium-Ion Batteries. IEEE Transactions on Instrumentation and Measurement, 2017, 66, 280-293.	2.4	106
64	Characterization of Hygroscopic Swelling Behavior of Mold Compounds and Plastic Packages. IEEE Transactions on Components and Packaging Technologies, 2004, 27, 499-506.	1.4	105
65	A Hybrid Feature Selection Scheme for Reducing Diagnostic Performance Deterioration Caused by Outliers in Data-Driven Diagnostics. IEEE Transactions on Industrial Electronics, 2016, 63, 3299-3310.	5.2	102
66	Anomaly Detection Through a Bayesian Support Vector Machine. IEEE Transactions on Reliability, 2010, 59, 277-286.	3.5	99
67	Validation and verification of a hybrid method for remaining useful life prediction of lithium-ion batteries. Journal of Cleaner Production, 2019, 212, 240-249.	4.6	98
68	Hybrid electrochemical energy storage systems: An overview for smart grid and electrified vehicle applications. Renewable and Sustainable Energy Reviews, 2021, 139, 110581.	8.2	97
69	Physics-of-Failure-Based Prognostics and Health Management for High-Power White Light-Emitting Diode Lighting. IEEE Transactions on Device and Materials Reliability, 2011, 11, 407-416.	1.5	96
70	Interacting multiple model particle filter for prognostics of lithium-ion batteries. Microelectronics Reliability, 2017, 70, 59-69.	0.9	96
71	Prognostics implementation of electronics under vibration loading. Microelectronics Reliability, 2007, 47, 1849-1856.	0.9	94
72	Reliability of a k-out-of-n warm-standby system. IEEE Transactions on Reliability, 1992, 41, 72-75.	3.5	90

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73	Approach to Fault Identification for Electronic Products Using Mahalanobis Distance. IEEE Transactions on Instrumentation and Measurement, 2010, 59, 2055-2064.	2.4	90
74	Accelerated cycle life testing and capacity degradation modeling of LiCoO ₂ -graphite cells. Journal of Power Sources, 2019, 435, 226830.	4.0	89
75	<title>In-situ sensors for product reliability monitoring</title>. , 2002, , .		84
76	Aging characteristics-based health diagnosis and remaining useful life prognostics for lithium-ion batteries. ETransportation, 2019, 1, 100004.	6.8	81
77	Health Monitoring of Cooling Fans Based on Mahalanobis Distance With mRMR Feature Selection. IEEE Transactions on Instrumentation and Measurement, 2012, 61, 2222-2229.	2.4	80
78	Online Anomaly Detection for Hard Disk Drives Based on Mahalanobis Distance. IEEE Transactions on Reliability, 2013, 62, 136-145.	3.5	80
79	Prognostics uncertainty reduction by fusing on-line monitoring data based on a state-space-based degradation model. Mechanical Systems and Signal Processing, 2014, 45, 396-407.	4.4	78
80	A Review of Prognostic Techniques for High-Power White LEDs. IEEE Transactions on Power Electronics, 2017, 32, 6338-6362.	5.4	76
81	The "trouble not identified" phenomenon in automotive electronics. Microelectronics Reliability, 2002, 42, 641-651.	0.9	74
82	Enhanced Reliability Modeling of RAID Storage Systems. , 2007, , .		74
83	A multi-component and multi-failure mode inspection model based on the delay time concept. Reliability Engineering and System Safety, 2010, 95, 912-920.	5.1	74
84	Copper Wire Bonding Concerns and Best Practices. Journal of Electronic Materials, 2013, 42, 2415-2434.	1.0	74
85	Using cross-validation for model parameter selection of sequential probability ratio test. Expert Systems With Applications, 2012, 39, 8467-8473.	4.4	73
86	A Rotating Machinery Fault Diagnosis Method Based on Feature Learning of Thermal Images. IEEE Access, 2019, 7, 12348-12359.	2.6	73
87	Accelerated degradation model for C-rate loading of lithium-ion batteries. International Journal of Electrical Power and Energy Systems, 2019, 107, 438-445.	3.3	72
88	The Impact of Lead-Free Legislation Exemptions on the Electronics Industry. IEEE Transactions on Electronics Packaging Manufacturing, 2004, 27, 221-232.	1.6	68
89	Analysis of Manufacturing-Induced Defects and Structural Deformations in Lithium-Ion Batteries Using Computed Tomography. Energies, 2018, 11, 925.	1.6	68
90	In Situ Temperature Measurement of a Notebook Computer" A Case Study in Health and Usage Monitoring of Electronics. IEEE Transactions on Device and Materials Reliability, 2004, 4, 658-663.	1.5	67

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91	A Wireless Sensor System for Prognostics and Health Management. IEEE Sensors Journal, 2010, 10, 856-862.	2.4	67
92	In Situ Stress Measurement Techniques on Li-ion Battery Electrodes: A Review. Energies, 2017, 10, 591.	1.6	66
93	Tin whisker analysis of Toyota's electronic throttle controls. Circuit World, 2011, 37, 4-9.	0.7	65
94	High lead solder (over 85%) solder in the electronics industry: RoHS exemptions and alternatives. Journal of Materials Science: Materials in Electronics, 2015, 26, 4021-4030.	1.1	65
95	State of charge estimation based on a simplified electrochemical model for a single LiCoO ₂ battery and battery pack. Energy, 2017, 133, 572-583.	4.5	64
96	The significance of aqueous binders in lithium-ion batteries. Renewable and Sustainable Energy Reviews, 2021, 147, 111227.	8.2	63
97	A fusion prognostics method for remaining useful life prediction of electronic products. , 2009, , .		62
98	Warpage Analysis of Flip-Chip PBGA Packages Subject to Thermal Loading. IEEE Transactions on Device and Materials Reliability, 2009, 9, 419-424.	1.5	62
99	Algorithm to Determine the Knee Point on Capacity Fade Curves of Lithium-Ion Cells. Energies, 2019, 12, 2910.	1.6	61
100	Electronic device encapsulation using red phosphorus flame retardants. Microelectronics Reliability, 2006, 46, 53-62.	0.9	60
101	Reliability of Printed Circuit Boards Processed Using No-Clean Flux Technology in Temperature-Humidity-Bias Conditions. IEEE Transactions on Device and Materials Reliability, 2008, 8, 426-434.	1.5	60
102	The reliability physics approach to failure prediction modelling. Quality and Reliability Engineering International, 1990, 6, 267-273.	1.4	59
103	Are components still the major problem: a review of electronic system and device field failure returns. IEEE Transactions on Components, Hybrids and Manufacturing Technology, 1992, 15, 1160-1164.	0.4	59
104	Economic Analysis of Canary-Based Prognostics and Health Management. IEEE Transactions on Industrial Electronics, 2011, 58, 3077-3089.	5.2	59
105	Temperature dependent power capability estimation of lithium-ion batteries for hybrid electric vehicles. Energy, 2016, 113, 64-75.	4.5	59
106	Signal Model-Based Fault Coding for Diagnostics and Prognostics of Analog Electronic Circuits. IEEE Transactions on Industrial Electronics, 2017, 64, 605-614.	5.2	58
107	Remaining useful life estimation of lithium-ion cells based on k-nearest neighbor regression with differential evolution optimization. Journal of Cleaner Production, 2020, 249, 119409.	4.6	58
108	A model for moisture induced corrosion failures in microelectronic packages. IEEE Transactions on Components, Hybrids and Manufacturing Technology, 1990, 13, 383-389.	0.4	57

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109	Surface Insulation Resistance of Conformally Coated Printed Circuit Boards Processed With No-Clean Flux. IEEE Transactions on Electronics Packaging Manufacturing, 2006, 29, 217-223.	1.6	57
110	Intermetallics Characterization of Lead-Free Solder Joints under Isothermal Aging. Journal of Electronic Materials, 2008, 37, 1130-1138.	1.0	56
111	Model-based and data-driven prognosis of automotive and electronic systems. , 2009, , .		56
112	Prognostics-based risk mitigation for telecom equipment under free air cooling conditions. Applied Energy, 2012, 99, 423-429.	5.1	56
113	Preliminary Study on Integration of Fiber Optic Bragg Grating Sensors in Li-Ion Batteries and In Situ Strain and Temperature Monitoring of Battery Cells. Energies, 2017, 10, 838.	1.6	56
114	Identification of failure precursor parameters for Insulated Gate Bipolar Transistors (IGBTs). , 2008, , .		55
115	Early Detection of Interconnect Degradation by Continuous Monitoring of RF Impedance. IEEE Transactions on Device and Materials Reliability, 2009, 9, 296-304.	1.5	55
116	Ultrasonic Health Monitoring of Lithium-Ion Batteries. Electronics (Switzerland), 2019, 8, 751.	1.8	55
117	A machine learning-based framework for online prediction of battery ageing trajectory and lifetime using histogram data. Journal of Power Sources, 2022, 526, 231110.	4.0	55
118	Parameter selection for health monitoring of electronic products. Microelectronics Reliability, 2010, 50, 161-168.	0.9	54
119	A Prognostic Model for Stochastic Degrading Systems With State Recovery: Application to Li-Ion Batteries. IEEE Transactions on Reliability, 2017, 66, 1293-1308.	3.5	54
120	Statistical analysis of tin whisker growth. Microelectronics Reliability, 2006, 46, 846-849.	0.9	53
121	A Highly Accurate Method for Assessing Reliability of Redundant Arrays of Inexpensive Disks (RAID). IEEE Transactions on Computers, 2009, 58, 289-299.	2.4	52
122	Thermal Cycling Reliability of Lead-Free Solders (SAC305 and Sn3.5Ag) for High-Temperature Applications. IEEE Transactions on Device and Materials Reliability, 2011, 11, 328-338.	1.5	52
123	Physics-of-Failure: An Approach to Reliable Product Development. Journal of the Institute of Environmental Sciences, 1995, 38, 30-34.	0.0	52
124	The impact of electrical current, mechanical bending, and thermal annealing on tin whisker growth. Microelectronics Reliability, 2007, 47, 88-92.	0.9	51
125	Rare-Earth Elements in Lighting and Optical Applications and Their Recycling. Jom, 2013, 65, 1276-1282.	0.9	51
126	Health monitoring of cooling fan bearings based on wavelet filter. Mechanical Systems and Signal Processing, 2015, 64-65, 149-161.	4.4	51

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127	A Physics-Based Electrochemical Model for Lithium-Ion Battery State-of-Charge Estimation Solved by an Optimised Projection-Based Method and Moving-Window Filtering. <i>Energies</i> , 2018, 11, 2120.	1.6	51
128	Current Noise Cancellation for Bearing Fault Diagnosis Using Time Shifting. <i>IEEE Transactions on Industrial Electronics</i> , 2017, 64, 8138-8147.	5.2	50
129	Detection of Generalized-Roughness and Single-Point Bearing Faults Using Linear Prediction-Based Current Noise Cancellation. <i>IEEE Transactions on Industrial Electronics</i> , 2018, 65, 9728-9738.	5.2	50
130	Evaluation of built-in test. <i>IEEE Transactions on Aerospace and Electronic Systems</i> , 2001, 37, 266-271.	2.6	49
131	Health Assessment of Cooling Fan Bearings Using Wavelet-Based Filtering. <i>Sensors</i> , 2013, 13, 274-291.	2.1	49
132	An adaptive state of charge estimation approach for lithium-ion series-connected battery system. <i>Journal of Power Sources</i> , 2018, 392, 48-59.	4.0	49
133	Remaining useful life prediction for lithium-ion batteries based on an integrated health indicator. <i>Microelectronics Reliability</i> , 2018, 88-90, 1189-1194.	0.9	49
134	IEEE 1413: A Standard for Reliability Predictions. <i>IEEE Transactions on Reliability</i> , 2012, 61, 125-129.	3.5	48
135	Assessing time-to-failure due to conductive filament formation in multi-layer organic laminates. <i>IEEE Transactions on Advanced Packaging</i> , 1994, 17, 269-276.	0.7	47
136	A Review of Second-Life Lithium-Ion Batteries for Stationary Energy Storage Applications. <i>Proceedings of the IEEE</i> , 2022, 110, 735-753.	16.4	47
137	A New Member of the C-Type Lectin Family Is a Modulator of the Mast Cell Secretory Response. <i>International Archives of Allergy and Immunology</i> , 1995, 107, 82-86.	0.9	46
138	Health monitoring of electronic products based on Mahalanobis distance and Weibull decision metrics. <i>Microelectronics Reliability</i> , 2011, 51, 279-284.	0.9	46
139	A Patent Analysis of Prognostics and Health Management (PHM) Innovations for Electrical Systems. <i>IEEE Access</i> , 2018, 6, 18088-18107.	2.6	46
140	Recognition of protein substrates by the prolyl isomerase trigger factor is independent of proline residues 1 Edited by P. E. Wright. <i>Journal of Molecular Biology</i> , 1998, 277, 723-732.	2.0	45
141	An Assessment of Immersion Silver Surface Finish for Lead-Free Electronics. <i>Journal of Electronic Materials</i> , 2009, 38, 815-827.	1.0	45
142	Point-of-care biosensor system. <i>Frontiers in Bioscience - Scholar</i> , 2013, S5, 39-71.	0.8	45
143	Modeling of Combined Temperature Cycling and Vibration Loading on PBGA Solder Joints Using an Incremental Damage Superposition Approach. <i>IEEE Transactions on Advanced Packaging</i> , 2008, 31, 463-472.	1.7	44
144	Failure mechanisms based prognostics. , 2008, , .		44

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145	A Rapid Life-Prediction Approach for PBGA Solder Joints Under Combined Thermal Cycling and Vibration Loading Conditions. IEEE Transactions on Components and Packaging Technologies, 2009, 32, 283-292.	1.4	44
146	Visual inspection of steel surface defects based on domain adaptation and adaptive convolutional neural network. Mechanical Systems and Signal Processing, 2021, 153, 107541.	4.4	44
147	Field failure due to creep corrosion on components with palladium pre-plated leadframes. Microelectronics Reliability, 2003, 43, 775-783.	0.9	43
148	Environment and Usage Monitoring of Electronic Products for Health Assessment and Product Design. Quality Technology and Quantitative Management, 2007, 4, 235-250.	1.1	43
149	Prognostics and health management using physics-of-failure. , 2008, , .		43
150	An Options Approach for Decision Support of Systems With Prognostic Capabilities. IEEE Transactions on Reliability, 2012, 61, 872-883.	3.5	43
151	Ensemble-approaches for clustering health status of oil sand pumps. Expert Systems With Applications, 2012, 39, 4847-4859.	4.4	43
152	The Effect of Inverter Failures on the Return on Investment of Solar Photovoltaic Systems. IEEE Access, 2017, 5, 21336-21343.	2.6	43
153	Ion transport in encapsulants used in microcircuit packaging. IEEE Transactions on Components and Packaging Technologies, 2003, 26, 199-205.	1.4	42
154	Critical Review of the Engelmaier Model for Solder Joint Creep Fatigue Reliability. IEEE Transactions on Components and Packaging Technologies, 2009, 32, 693-700.	1.4	42
155	Disassembly methodology for conducting failure analysis on lithium-ion batteries. Journal of Materials Science: Materials in Electronics, 2011, 22, 1616-1630.	1.1	42
156	Tab Design and Failures in Cylindrical Li-ion Batteries. IEEE Access, 2019, 7, 24082-24095.	2.6	42
157	Aging modes analysis and physical parameter identification based on a simplified electrochemical model for lithium-ion batteries. Journal of Energy Storage, 2020, 31, 101538.	3.9	42
158	Imbalanced bearing fault diagnosis under variant working conditions using cost-sensitive deep domain adaptation network. Expert Systems With Applications, 2022, 193, 116459.	4.4	42
159	Electrostatic Monitoring of Gas Path Debris for Aero-engines. IEEE Transactions on Reliability, 2011, 60, 33-40.	3.5	41
160	Anomaly Detection of Light-Emitting Diodes Using the Similarity-Based Metric Test. IEEE Transactions on Industrial Informatics, 2014, 10, 1852-1863.	7.2	41
161	<i>In-Situ</i> Observations of Lithium Dendrite Growth. IEEE Access, 2018, 6, 8387-8393.	2.6	41
162	Product Reliability, Maintainability, and Supportability Handbook. , 0, , .		41

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181	Are you ready for lead-free electronics?. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 884-894.	1.4	37
182	Prognostics implementation methods for electronics. , 2007, , .		37
183	Prognostics of Failures in Embedded Planar Capacitors using Model-Based and Data-Driven Approaches. Journal of Intelligent Material Systems and Structures, 2011, 22, 1293-1304.	1.4	37
184	Economics of rare earth elements in ceramic capacitors. Ceramics International, 2012, 38, 6091-6098.	2.3	37
185	Identification of Failure Mechanisms to Enhance Prognostic Outcomes. Journal of Failure Analysis and Prevention, 2012, 12, 66-73.	0.5	37
186	Predicting Damage and Life Expectancy of Subsea Power Cables in Offshore Renewable Energy Applications. IEEE Access, 2019, 7, 54658-54669.	2.6	37
187	Placement for reliability and routability of convectively cooled PWBs. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 1990, 9, 734-744.	1.9	36
188	In-situ measurements of surface mount IC package deformations during reflow soldering. IEEE Transactions on Components, Packaging and Manufacturing Technology Part C Manufacturing, 1997, 20, 207-212.	0.4	36
189	Chinese science and technology â€” Structure and infrastructure. Technological Forecasting and Social Change, 2007, 74, 1539-1573.	6.2	36
190	Prognostics of lithium-ion batteries using model-based and data-driven methods. , 2012, , .		36
191	On physical-layer concepts and metrics in secure signal transmission. Physical Communication, 2017, 25, 14-25.	1.2	36
192	Moisture ingress into organic laminates. IEEE Transactions on Components and Packaging Technologies, 1999, 22, 104-110.	1.4	35
193	Handbook of Electronic Package Design. Journal of Electronic Packaging, Transactions of the ASME, 2000, 122, 178-179.	1.2	35
194	Characterization of plastic encapsulant materials as a baseline for quality assessment and reliability testing. Microelectronics Reliability, 2002, 42, 1163-1170.	0.9	35
195	Lead-free soldering in the Japanese electronics industry. IEEE Transactions on Components and Packaging Technologies, 2003, 26, 616-624.	1.4	35
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